



Material Content Data Sheet



Sales Product Name	SAK-XC167CI-16F40F BB			Issued		24. September 2019		
MA#	MA001322916							
Package	PG-TQFP-144-7			Weight*		1403.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	28.260	2.01	2.01	20141	20141
leadframe	non noble metal	magnesium	7439-95-4	0.529	0.04		377	
	inorganic material	silicon	7440-21-3	2.293	0.16		1634	
	non noble metal	nickel	7440-02-0	10.581	0.75		7541	
	non noble metal	copper	7440-50-8	339.310	24.18	25.13	241821	251373
wire	noble metal	gold	7440-57-5	4.190	0.30	0.30	2986	2986
encapsulation	organic material	carbon black	1333-86-4	4.995	0.36		3560	
	plastics	epoxy resin	-	134.875	9.61		96124	
	inorganic material	silicondioxide	60676-86-0	859.207	61.24	71.21	612345	712029
leadfinish	non noble metal	tin	7440-31-5	8.638	0.62	0.62	6156	6156
plating	noble metal	silver	7440-22-4	4.833	0.34	0.34	3445	3445
glue	plastics	epoxy resin	-	1.086	0.08		774	
	noble metal	silver	7440-22-4	4.344	0.31	0.39	3096	3870
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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